SUPPLEMENTAL SECTION

Exemplary specification support for amended and new claims:

1. (Currently Amended) A surface mountable clip, comprising:

a metal structure having a plurality of planar sides generally formed into a U-shape;

an opening formed by the metal structure being sized to receive and retain an electrical component;

a bottom planar side of the metal structure for mounting the generally U-shaped metal structure on a solder pad of a printed circuit board (PCB), such that the clip is free to rotate over molten solder formed on the solder pad during a reflow soldering process; and ***[see FIG. 3 and 10, page 4 at lines 20-22, page 5 at lines 7-9, page 6 at lines 24-27]***

a hole formed through the bottom planar side which is adapted to break a surface tension of the molten solder during the reflow soldering process. ***[see page 4 at lines 24-30, page 6 at lines 27-31, original claim 2 on page 14 at lines 12-14]***

2. (Currently Amended) The surface mountable clip of claim 1, wherein the hole formed through the bottom planar side is configured to ~~break a surface tension of molten solder over a solder pad of the PCB during a reflow soldering process~~ allow the bottom planar side to sink into the molten solder during the reflow soldering process. ***[see page 5 at lines 10-12]***

3. (Original) The surface mountable clip of claim 1, further comprising:

a first leg extending laterally from the bottom planar side.

4. (Original) The surface mountable clip of claim 1, further comprising:

a first leg extending laterally from a first edge of the bottom planar side; and

a second leg extending laterally from a second edge of bottom first planar side which is opposite the first edge.

5. (Original) The surface mountable clip of claim 1, further comprising:

a first notch formed along a first edge of the bottom planar side.

6. (Original) The surface mountable clip of claim 1, wherein the generally U-shaped metal structure is a single integrally formed structure.

7. (Original) The surface mountable clip of claim 1, wherein the generally U-shaped metal structure comprises a polygon-shaped metal structure.

8. (Currently Amended) The surface mountable clip of claim 1, wherein the ~~generally U-shaped metal structure is formed with at least seven planar sides~~ surface mountable clip facilitates a grounding of the electrical component on the PCB. ***[see page 12 at lines 32-33]***

9. (Original) The surface mountable clip of claim 1, comprising an antenna clip configured to receive and retain an electrical component comprising an antenna.

10. (Currently Amended) The surface mountable clip of claim 1, further comprising:

a first leg extending laterally from the bottom planar side; and

wherein the first leg is utilized by a vision system to position the clip onto ~~a printed circuit board (PCB)~~ the PCB.

11. (Currently Amended) A printed circuit board (PCB) comprising:

a substrate;

a solder pad formed over the substrate;

a surface mountable clip which includes:

a metal structure having a plurality of planar sides generally formed into a U-shape;

an opening formed by the generally U-shape metal structure being sized to receive and retain an electrical component;

a bottom planar side which is mounted over the solder pad to support the generally U-shaped metal structure, such that the clip is free to rotate over molten solder formed on the solder pad during a reflow soldering process; and ***[see FIG. 3 and 10, page 4 at lines 20-22, page 5 at lines 7-9, page 6 at lines 24-27]***

a hole formed through the bottom planar side which is adapted to break a surface tension of the molten solder during the reflow soldering process. ***[see page 4 at lines 24-30, page 6 at lines 27-31, original claim 2 on page 14 at lines 12-14]***

12. (Original) The PCB of claim 11, wherein the clip further comprises:

a first leg extending laterally from the first planar side.

13. (Original) The PCB of claim 11, wherein the clip further comprises:

a first leg extending laterally from a first edge of the first planar side; and

a second leg extending laterally from a second edge of the first planar side which is opposite the first edge.

14. (Original) The PCB of claim 11, wherein the clip further comprises:
a first notch formed along a first edge of the bottom planar side.

15. (Original) The PCB of claim 11, wherein the generally U-shaped metal structure is a single integrally formed structure.

16. (Original) The PCB of claim 11, wherein the generally U-shaped metal structure comprises a polygon-shaped metal structure.

17. (Original) The PCB of claim 11, wherein the generally U-shaped metal structure has at least seven planar sides.

18. (Currently Amended) The PCB of claim 11, wherein the ~~generally U-shaped metal structure has at least seven planar sides~~ surface mountable clip facilitates a grounding of the electrical component on the PCB. ***[see page 12 at lines 32-33]***

19. (Original) The PCB of claim 11, further comprising:
a first leg extending laterally from the bottom planar side; and
wherein the first leg is utilized by a vision system to position the clip onto the PCB.

20. (Original) The PCB of claim 11, further comprising a second surface mountable clip mounted on the PCB for further retaining the electrical component.

21. (Currently Amended) A mobile communication device comprising:
a printed circuit board (PCB);
a radio frequency (RF) transceiver carried on the PCB;
an antenna coupled to the RF transceiver;
at least one surface mountable antenna clip carried on the PCB which retains the antenna;
the at least one surface mountable antenna clip including:
a metal structure having a plurality of planar sides generally formed into a U-shape;
an opening formed by the generally U-shape metal structure being sized to receive and retain the antenna;

a bottom planar side which is mounted over a solder pad on the PCB to support the generally U-shaped metal structure, such that the clip is free to rotate over a molten solder formed on the solder pad during a reflow soldering process; and ***[see FIG. 3 and 10, page 4 at lines 20-22, page 5 at lines 7-9, page 6 at lines 24-27]***

a hole formed through the bottom planar side which is adapted to break a surface tension of the molten solder during the reflow soldering process. ***[see page 4 at lines 24-30, page 6 at lines 27-31, original claim 2 on page 14 at lines 12-14]***

22. (Original) The mobile communication device of claim 21, wherein the clip further comprises:

a first leg extending laterally from the first planar side.

23. (Original) The mobile communication device of claim 21, wherein the clip further comprises:

a first leg extending laterally from a first edge of the first planar side; and

a second leg extending laterally from a second edge of the first planar side which is opposite the first edge.

24. (Original) The mobile communication device of claim 21, wherein the clip further comprises:

a first notch formed along a first edge of the bottom planar side.

25. (Original) The mobile communication device of claim 21, wherein the generally U-shaped metal structure is a single integrally formed structure.

26. (Original) The mobile communication device of claim 21, wherein the generally U-shaped metal structure comprises a polygon-shaped metal structure.

27. (Currently Amended) The mobile communication device of claim 21, wherein the ~~generally U-shaped metal structure is formed with at least seven planar sides~~ surface mountable clip facilitates a grounding of the antenna on the PCB. ***[see page 12 at lines 32-33]***

28. (Original) The mobile communication device of claim 21, wherein the bottom planar side is generally rectangular.

29. (Original) The mobile communication device of claim 21, wherein the at least one surface mountable antenna clip comprises a second surface mountable antenna clip for further retaining the antenna.

30. (Original) The mobile communication device of claim 21, further comprising:
a first leg extending laterally from the bottom planar side; and
wherein the first leg is utilized by a vision system to position the clip onto the PCB.